

Tin Ingot Product Parameter Table

Product Model	Main Component Content (Sn)	Impurity Content (≤)	Appearance Quality	Dimension Specification (mm)	Single Weight (kg)	Density (g/cm ³)	Melting Point (°C)	Executive Standard	Application Field
Sn99.99	≥99.99%	Pb: 0.005%, Fe: 0.002%, Cu: 0.001%, As: 0.001%, Sb: 0.001%, Total Other Impurities: 0.001%	Smooth surface, no oxidation, no slag inclusion, no cracks, uniform silvery white color	Standard: 500×100×50, custom special dimensions available	20±0.5	7.28	231.93	GB/T 728-2010	Electronic components, welding materials, food packaging materials, electroplating industry
Sn99.95	≥99.95%	Pb: 0.02%, Fe: 0.005%, Cu: 0.003%, As: 0.002%, Sb: 0.002%, Total Other Impurities: 0.02%	Clean surface, no obvious oxidation spots, no visible inclusions, regular shape	Standard: 500×100×50, custom special dimensions available	20±0.5	7.27	231.93	GB/T 728-2010	Alloy manufacturing, bearing alloys, solder wire production, chemical catalysts
Sn99.90	≥99.90%	Pb: 0.05%, Fe: 0.01%, Cu: 0.005%, As: 0.003%, Sb: 0.003%, Total Other Impurities: 0.04%	Minor oxide film allowed on surface, no cracks, no large particle slag, intact shape	Standard: 500×100×50, custom special dimensions available	20±0.5	7.26	231.93	GB/T 728-2010	Battery plates, hardware accessories, printing alloys, tin alloy castings
High Purity Sn99.999	≥99.999%	Pb: 0.0005%, Fe: 0.0002%, Cu: 0.0001%, As: 0.0001%, Sb: 0.0001%, Total Other Impurities: 0.0005%	Ultra-high cleanliness, no oxidation or impurity adhesion on surface, bright and uniform color	Custom dimensions: Processed according to customer needs, standard 300×80×40	10±0.2	7.29	231.93	GB/T 728-2010 (Refined Standard)	Semiconductor materials, high-end electronic chips, aerospace components, precision instrument manufacturing